

AMENDMENTS TO THE CLAIMS

The following listing of the claims replaces all prior claims presented in the application.

1. (Currently amended) A composition comprising:
 - i) a fragrance composition comprising
 - a) at least 10.0% by weight of a fragrance composition of one or more perfume ingredients having a boiling point of 250°C or less and ClogP of less than 3.0;
 - b) at least 15% by weight of a fragrance composition of one or more perfume ingredients having a boiling point of 250°C or less and ClogP of 3.0 or more; and
 - c) at least 20% by weight of a fragrance composition of one or more perfume ingredients have a boiling point of greater than 250°C; and
 - ii) a silicone-in-water emulsion comprising at least one surfactant, wherein the dispersed silicone is substantially linear, has a viscosity of 100 million mm^2s^{-1} or more and a particle size of 2 μm or less.
2. (Original) The composition of claim 1, wherein the silicone-in-water emulsion is non-ionic and the silicone is a linear polysiloxane polysilalkylene copolymer, wherein the monovalent silicone substituents are substantially all C_{1-6} hydrocarbon groups and the copolymer has a viscosity of 150 million mm^2s^{-1} or more and a particle size of 1 μm or less.
3. (Previously Presented) The composition of claim 2, wherein the silicone-in-water emulsion is a non-ionic emulsion comprising about 60 % by weight of a linear silicone copolymer formed by the hydrosilylation of a Si-H end-blocked polydimethyl siloxane and a vinyl-end-blocked polydimethyl siloxane, wherein the copolymer has a viscosity of about 170 million mm^2s^{-1} and a particle size of about 0.5 μm , and about 5 % by weight of non-ionic surfactants.
4. (Currently Amended) The composition of claim 1, wherein said fragrance composition comprises:
 - a) at least 10.0% by weight of a fragrance composition of one or more perfume ingredients having a boiling point of 250 °C or less and ClogP of less than 3.0,

b) at least 20% by weight of a fragrance composition of one or more perfume ingredients having a boiling point of 250 °C or less and ClogP of 3.0 or more, and

c) at least 30% by weight of a fragrance composition of one or more perfume ingredients have a boiling point of greater than 250 °C, ~~÷ and~~

5. (Previously Presented) The composition of claim 1, wherein said fragrance composition comprises:

a) at least 20.0% by weight of the fragrance composition of one or more perfume ingredients having a boiling point of 250 °C or less and ClogP of less than 3.0;

b) at least 15% by weight of the fragrance composition of one or more perfume ingredients having a boiling point of 250 °C or less and ClogP of 3.0 or more; and

c) at least 30% by weight of the fragrance composition of one or more perfume ingredients have a boiling point of greater than 250 °C.

6. (Previously Presented) The composition of claim 1, wherein said fragrance composition comprises:

a) 30.0 to 40.0 % by weight of the fragrance composition of one or more perfume ingredients having a boiling point of 250 °C or less and ClogP of less than 3.0;

b) 20.0 to 25.0 % by weight of the fragrance composition of a one or more perfume ingredients having a boiling point of 250 °C or less and ClogP of 3.0 or more; and

c) 40.0 to 45.0 % by weight of the fragrance composition of one or more perfume ingredients have a boiling point of greater than 250 °C.

7. (Previously Presented) The composition of claim 1, wherein the silicone:fragrance composition weight ratio is from 1:1 to 10:1.

8. (Previously Presented) A hair care preparation comprising a composition according to claim 1.

9. (Original) The hair care preparation of claim 8, wherein the hair care preparation is a shampoo, a conditioner, or a conditioning shampoo.

10. (Previously Presented) A method of cleansing hair, which comprises applying to the hair a hair care preparation according to claim 8.

11. (Previously Presented) A method of depositing fragrance on hair, which comprises applying to the hair a hair care preparation according to claim 8.